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# **USB Type-C EMCA Controller**

#### **General Description**

EZ-PD™ CMG1 is a dedicated USB Type-C EMCA controller that complies with the USB Type-C and Power Delivery (PD) standards for Electronically Marked Type-C Thunderbolt and non-Thunderbolt passive cable applications. EZ-PD CMG1 integrates a complete Type-C transceiver including the R<sub>A</sub> termination resistors on the VCONN pins and VBUS short circuit protection on both VCONN and CC pins. CMG1 also includes 40 bytes of storage for configuration of vendor-, device-, and cable-specific configuration data. EZ-PD CMG1 is targeted for passive EMCA implementations with either one or two e-marker chips on the cable.

#### **Features**

#### Type-C Support and USB-PD Support

- Supports USB PD3.0 spec and USB Type-C spec version 1.3 (Including support for the revised minimum VCONN operating voltage of 3 V)
- Integrated high-voltage protection on CC, VCONN1, and VCONN2 pins to protect against accidental shorts to the VBUS pin on the Type-C connector
- 40-byte storage programmable over Type-C interface for storing vendor-, device-, and cable-specific configuration data
- Termination resistor R<sub>A</sub> on VCONN1 and VCONN2
- Supports R<sub>A</sub> weakening to reduce power consumption
- Supports electronically marked passive cable implementations with one or two controllers

#### **Clocks and Oscillators**

■ Integrated oscillator eliminating the need for external clock

#### **Power**

- 2.7 V to 5.5 V operation
- Sleep: 1.7 mA

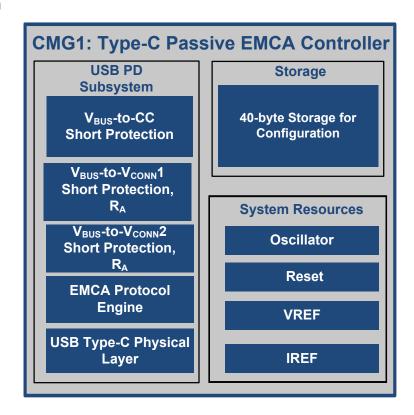
#### **System-Level ESD Protection**

- On CC, VCONN1, and VCONN2 pins
- ± 8 kV Contact Discharge and ±15 kV Air Gap Discharge based on IEC61000-4-2 level 4C

#### **Package**

- 9-ball WLCSP
- Supports industrial temperature range (-40 °C to +85 °C)

## Logic Block Diagram



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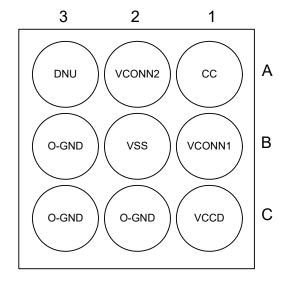


#### **Pinout**

Table 1. 9-Ball CSP Pin Description

9-Ball CSP	Pin Name	Description
A1	CC	Communication Channel (VBUS short protected)/IEC
A2	VCONN2	VCONN2 supply with R <sub>A</sub> termination (2.7 V to 5.5 V) (VBUS Short protected)/IEC
A3	DNU <sup>[1]</sup>	Do not use <sup>[1]</sup>
B1	VCONN1	VCONN1 supply with R <sub>A</sub> termination (2.7 V to 5.5 V) (VBUS Short protected)/IEC
B2	VSS	Ground pin. Mandatory to connect to system GND
В3	O-GND <sup>[2]</sup>	Optional GND pin. This pin can be connected to the system GND for better board layout routability.
C1	VCCD	1.8-V Core Voltage Out. Connect to 1-μF capacitor
C2	O-GND <sup>[2]</sup>	Optional GND pin. This pin can be connected to system GND for better board layout routability.
C3	O-GND <sup>[2]</sup>	Optional GND pin. This pin can be connected to system GND for better board layout routability.

Figure 1. Pinout of 9-WLCSP Bottom (Balls Up) View



- Keep pin A3 floating for all passive EMCA applications. See Figure 4 and Figure 5 for more details.
   Any of the optional GND pins B3, C2, and C3 can be connected to system GND for better board layout routability. If connected to GND, ensure that the selected pin/s are shorted with the VSS pin (B2) of the CMG1 device in their board layout. If users are not planning to connect these optional GND pins to system GND, then it is mandatory to leave them unconnected in their board designs.



## **Power**

Figure 2 shows an overview of the CMG1 power system requirement. CMG1 operates from two possible external supply sources, VCONN1 and VCONN2. The VCONN supplies support operation over 2.7 V–5.5 V. CMG1 has two different power modes: Active and Sleep, transitions between which are managed by the Power System. The VCCD pin, the output of the core regulator (1.8 V), is brought out for connecting a 1-μF capacitor for regulator stability only. This pin is not supported as a power supply.

V<sub>CONN2</sub>

1 uF

1.8-V Regulator

V<sub>CCD</sub>

1 uF

V<sub>CSNN2</sub>

1 uF

V<sub>CCD</sub>

1 uF

Figure 2. Power System



#### CMG1 Application Configuration Update Over CC Interface

The CMG1 Manufacturing Test Kit (MTK) Utility is used for updating the configuration parameters of the CMG1 devices over the CC interface. The CMG1 MTK Utility is integrated as a part of the EZ-PD Configuration Utility and is supported by its version 1.1 Beta (or later). Vendor-specific and cable-specific parameters can be set using the EZ-PD Configuration Utility. Once the parameters are set, the CMG1 MTK Utility is used for configuration and testing of CMG1-based passive EMCA cables.

To use the CMG1 MTK Utility, you must use the CY4532 EZ-PD CCG3PA EVK as shown in a high-level block diagram in Figure 3. The CMG1 MTK Utility is accompanied with a CMG1 MTK-specific firmware solution, which is intended for the CCG4 device present on the CY4532 EZ-PD CCG3PA EVK's Power Board. If customers are using the CY4532 EZ-PD CCG3PA EVK for the first time to update the configuration parameters of CMG1 devices, then the CCG4 device's firmware needs to be updated to this MTK-specific firmware (detailed instructions are provided in Getting Started with EZ-PD CMG1 Application Note).

The EZ-PD Configuration Utility 1.1 Beta (or later), which integrates and supports the CMG1 MTK Utility, can be downloaded here. For further details, follow the instructions provided in Getting Started with EZ-PD CMG1 Application Note for hardware setup and step-by-step instructions. Also, see Chapter 4 of the EZ-PD Configuration Utility User Manual for more details on how to configure and test CMG1-based passive EMCA cables.

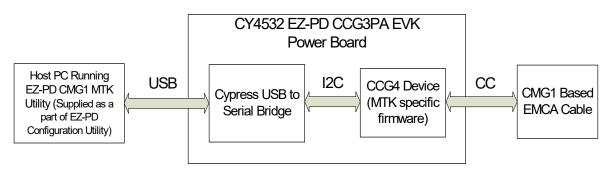


Figure 3. CMG1 Application Configuration Update Over CC Interface

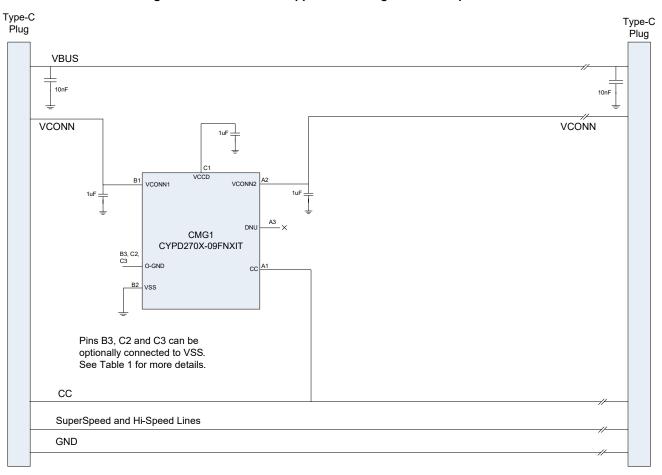


#### **Application Diagrams**

Figure 4 and Figure 5 show the application diagrams of a Passive EMCA application using CMG1 devices. Figure 4 shows the application using a single CMG1 device per cable present at one of the two plugs, whereas Figure 5 shows the same with two CMG1 devices per cable present at each plug. The VBUS signal, the SuperSpeed lines, Hi-Speed lines, and CC lines are connected directly from one end to another. The application

diagram shown in Figure 4 requires a single VCONN wire to run through the cable so that the CMG1 device can be powered irrespective of which plug is connected to the host (DFP). However, in the application diagram shown in Figure 5, the VCONN signal does not run through the entire cable, but only runs to the respective VCONN pin of the CMG1 device at each end of the plug. Also, only one CMG1 device is powered at any given instance, depending on which one is nearer to the DFP that supplies VCONN.

Figure 4. Passive EMCA Application - Single CMG1 Chip Per Cable





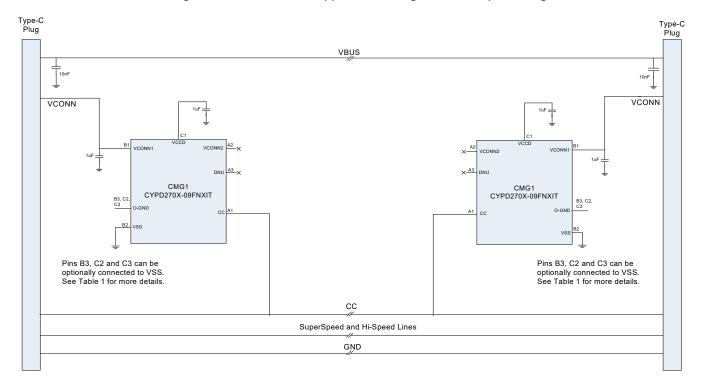


Figure 5. Passive EMCA Application - Single CMG1 Chip Per Plug



# **Electrical Specifications**

## **Absolute Maximum Ratings**

## Table 2. Absolute Maximum Ratings

Parameter	Description	Min	Тур	Max	Units	Details/Conditions
V <sub>CONN_MAX</sub>	Max supply voltage relative to V <sub>SS</sub>	_	_	25	V	Absolute max
V <sub>CC_PIN_ABS</sub>	Max voltage on the CC pin	-	_	25	V	Absolute max
ESD_HBM	Electrostatic discharge human body model	2200	_	-	V	-
ESD_CDM	Electrostatic discharge charged device model	500	_	-	V	-
LU	Pin current for latch-up	-140	_	140	mA	_
ESD_IEC_CON	Electrostatic discharge IEC61000-4-2	8000	_	_	V	Contact discharge on CC and V <sub>CONN</sub> pins
ESD_IEC_AIR	Electrostatic discharge IEC61000-4-2	15000	_	_	V	Air discharge for CC and V <sub>CONN</sub> pins

## **Device-Level Specifications**

See basic specifications in the following tables. More specifications will be added in a future version of this document.

Table 3. DC Specifications

Spec ID	Parameter	Description	Min	Тур	Max	Units	Details/Conditions
SID.PWR#1	V <sub>CONN1</sub> or V <sub>CONN2</sub>	Power supply input voltage 2.7 – 5.5		5.5	٧	-	
SID.PWR#5	$V_{CCD}$	Output voltage (for core logic)	_	1.8	_	V	_
SID.PWR#12	C <sub>EFC</sub>	External regulator voltage bypass on V <sub>CCD</sub>	0.8	1	1.2	μF	X5R ceramic or better
SID.PWR#13	C <sub>VCONN</sub>	Power supply decoupling capacitor on $V_{CONN1}$ and $V_{CONN2}$	0.8	1	_	μF	X5R ceramic or better
Active Mode, V <sub>C</sub>	ONN1 or V <sub>CO</sub>	$_{\rm NN2}$ = 2.7 V to 5.5 V. Typical values	measur	ed at V <sub>0</sub>	CONN1 OF	V <sub>CONN2</sub>	= 5 V
SID.PWR#8	I <sub>DD_A</sub>	Active current	-	5	7.5	mA	CC I/O in Transmit or Receive
Sleep Mode, Typical values measured at V <sub>CONN1</sub> or V <sub>CONN2</sub> = 5 V and T <sub>A</sub> = 25 °C							
SID25A	I <sub>DD_S</sub>	Sleep mode current	ı	1.7	3.0	mA	CC as wakeup source. One VCONN supply is powered, the other is floating or grounded.



## Table 4. PD DC Specifications

Spec ID	Parameter	Description	Min	Тур	Max	Units	Details/Conditions
SID.PD.6	R <sub>A</sub>	Power cable termination	0.8	1	1.2	kΩ	All supplies force to 0 V and 0.2 V applied at V <sub>CONN1</sub> or V <sub>CONN2</sub>
SID.PD.7	R <sub>A_OFF</sub>	Power cable termination - disabled	0.4	0.75	_	МΩ	2.7 V applied at V <sub>CONN1</sub> or V <sub>CONN2</sub> with R <sub>A</sub> disabled
SID.PD.14	I <sub>LEAK</sub>	Leaker on V <sub>CONN1</sub> or V <sub>CONN2</sub> for discharge upon cable detach	150	-	_	μA	-
SID.PD.15	V <sub>GNDOFST</sub>	Ground offset tolerated by BMC receiver	-500	-	500	mV	Relative to remote BMC transmitter
SID.PD.16	Z <sub>OPEN_PD</sub>	Impedance of CC pin with VCONN1 and VCONN2 un-powered	200	-	_	kΩ	0 V ≤ CC Voltage ≤ 5.5 V

## **Table 5. Storage Specifications**

Spec ID	Parameter	Description	Min	Тур	Max	Units	Details/Conditions
SID.MEM#3	NVL_ERASE	NVL bulk erase time	25	-	100	ms	-40 °C ≤ T <sub>Δ</sub> ≤ 85 °C
SID.MEM#4	NVL_WRITE	NVL program	2	_	10	ms	1-40 C \(\frac{1}{A}\) \(\frac{5}{60}\) C
SID.MEM#5	NVL_DR	NVL data retention	20	_	_	years	$25  ^{\circ}\text{C} \le \text{T}_{\text{A}} \le 55  ^{\circ}\text{C}$
SID.MEM#5A	NVL_DR	NVL data retention	10	_	_	years	55 °C ≤ T <sub>A</sub> ≤ 85 °C
SID.MEM#6	NVL_ENPB	NVL write endurance	100	_	_	cycles	$25  ^{\circ}\text{C} \le T_{A} \le 55  ^{\circ}\text{C}$



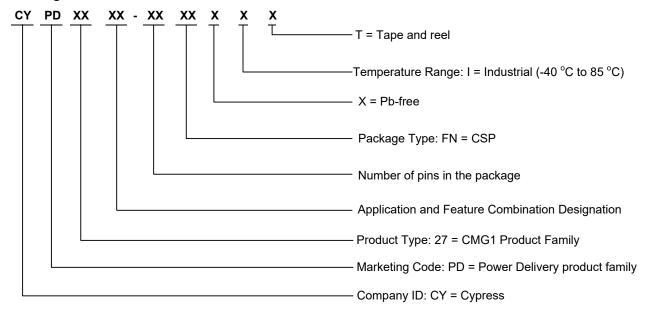
## **Ordering Information**

Table 6 lists the EZ-PD CMG1 part numbers and features.

Table 6. CMG1 Ordering Information

MPN	Application	Type-C Ports	Role	Package Type	Si ID
CYPD2703-09FNXIT	Passive Cable	1	EMCA	9-ball CSP	2600
CYPD2704-09FNXIT	Thunderbolt Passive Cable	1	EMCA	9-ball CSP	2601

#### **Ordering Code Definition**





# **Packaging**

## **Table 7. Package Characteristics**

Parameter	Description	Conditions	Min	Тур	Max	Units
T <sub>A</sub>	Operating ambient temperature	Industrial	-40	25	85	°C
T <sub>J</sub>	Operating junction temperature	Industrial	-38.68	26.32	86.32	°C
$T_JA$	Package θ <sub>JA</sub> (9-pin CSP)		_	_	31.9	°C/W
T <sub>JC</sub>	Package θ <sub>JC</sub> (9-pin CSP)		-		20.02	°C/W

#### Table 8. Solder Reflow Peak Temperature

Package	Maximum Peak Temperature	Maximum Time within 5 °C of Peak Temperature
9-pin CSP	260 °C	30 seconds

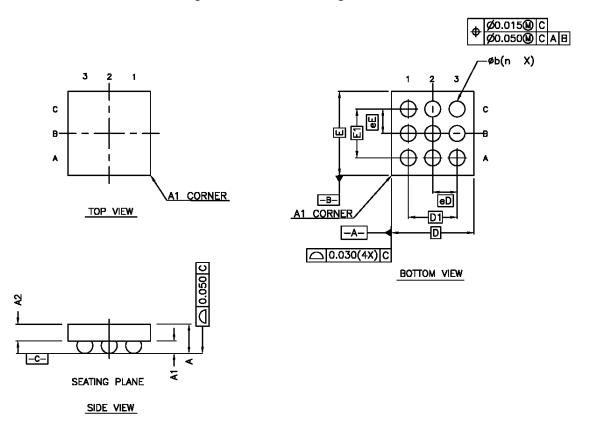
## Table 9. Package Moisture Sensitivity Level (MSL), IPC/JEDEC J-STD-2

Package	MSL
9-pin CSP	MSL 1

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Figure 6. 9-ball CSP Package Outline



SYMBOL	DIMENSIONS				
STMBOL	MIN.	NOM.	MAX.		
Α	ı	-	0.520		
A1	0.122	0.152	0.182		
A2	0.250	0.275	0.300		
D	1.351 BSC				
E	1	.376 BS	C		
D1	0	.800 BS	С		
E1	0	.800 BS	C		
n	9				
Øb	0.188	0.218	0.248		
eD	0.400 BSC				
əЕ	0.400 BSC				

#### <u>NOTES</u>

1. ALL DIMENSIONS ARE IN MILLIMETERS.

002-21607 \*B



## **Acronyms**

Table 10. Acronyms Used in this Document

Acronym	Description			
CC	configuration channel			
CPU	central processing unit			
DFP	downstream facing port			
DRP	dual role port			
EMCA	electronically marked cable assembly, a USB cable that includes an IC that reports cable characteristics (e.g., current rating) to the Type-C ports			
ESD	electrostatic discharge			
IC	integrated circuit			
MCU	microcontroller unit			
NC	no connect			
NVL	non-volatile latch			
PD	power delivery			
PHY	physical layer			
POR	power-on reset			
PSoC <sup>®</sup>	Programmable System-on-Chip™			
RX	receive			
TX	transmit			
Type-C	a new standard with a slimmer USB connector and a reversible cable, capable of sourcing up to 100 W of power			
USB	Universal Serial Bus			

## **Document Conventions**

#### **Units of Measure**

Table 11. Units of Measure

Symbol	Unit of Measure			
°C	degrees Celsius			
Hz	hertz			
KB	1024 bytes			
kHz	kilohertz			
kΩ	kilo ohm			
Mbps	megabits per second			
MHz	megahertz			
ΜΩ	mega-ohm			
Msps	megasamples per second			
μΑ	microampere			
μF	microfarad			
μs	microsecond			
μV	microvolt			
μW	microwatt			
mA	milliampere			
ms	millisecond			
mV	millivolt			
nA	nanoampere			
ns	nanosecond			
Ω	ohm			
pF	picofarad			
ppm	parts per million			
ps	picosecond			
s	second			
sps	samples per second			
V	volt			



# **Document History Page**

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Revision	ECN	Orig. of Change	Submission Date	Description of Change			
*H	6242326	VGT	07/13/2018	Changed datasheet status to Final.			
*	6554744	VGT	04/24/2019	Updated 9-ball CSP package diagram.			

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